## IN THE CLAIMS

Please amend and consider the claims as follows:

- 1. (Currently Amended) An apparatus, comprising:
  - a unitary capacitor having a bottom surface, a top surface, and an aperture in a central portion thereof extending from the top surface to the bottom surface; and
  - wherein the bottom surface is provided with electrical connections adapted to be connected to a substrate, and
  - wherein the unitary capacitor is configured such that when the unitary capacitor is

    disposed on a top surface of a package substrate, a surface area of an

    uncovered peripheral portion of the top surface of the package substrate is

    no greater than 21% of a total surface area of the top surface of the

    package substrate, the uncovered peripheral portion defined as a surface

    area of the top surface of the package substrate between an outside

    perimeter of the unitary capacitor and a perimeter of the package substrate.
- 2. (Previously Presented) The apparatus of Claim 1, wherein the aperture is rectangular.
- 3. (Previously Presented) The apparatus of Claim 1, wherein the unitary capacitor comprises a layer of an electrically conductive material and a layer of a dielectric material.

- 4. (Previously Presented) The apparatus of Claim 3, wherein a housing of the unitary capacitor is made from a plastic material.
- 5. (Previously Presented) The apparatus of Claim 1, wherein said electrical connections provided on the bottom surface comprise a ball grid array.
- 6. (Previously Presented) The apparatus of Claim 1, wherein the unitary capacitor comprises co-fired ceramic.
- 7. (Previously Presented) The apparatus of Claim 1, wherein the aperture is configured to fit over a semiconductor die, and wherein said electrical connections are configured for connection to a package substrate on which the semiconductor die is mounted.
- (Currently Amended) A semiconductor package assembly, comprising:
   a semiconductor die mounted on a portion of a top surface of a package substrate;
   and
  - a unitary windowframe capacitor having an aperture formed therein, and mounted on the top surface of the package substrate surrounding the semiconductor die,—wherein—the—unitary—windowframe—capacitor—is—arranged—to substantially cover an available area of the top surface of the package substrate

wherein a surface area of an uncovered peripheral portion of the top surface of the

package substrate is no greater than 21% of a total surface area of the top surface of the package substrate, the uncovered peripheral portion defined as a surface area of the top surface of the package substrate between an outside perimeter of the unitary windowframe capacitor and a perimeter of the package substrate.

- 9. (Original) The semiconductor package assembly of Claim 8, further comprising an electronic component mounted on a top surface of the windowframe capacitor.
- 10. (Original) The semiconductor package assembly of Claim 8, further comprising a second windowframe capacitor mounted on a top surface of the first windowframe capacitor.
- 11. (Original) The semiconductor package assembly of Claim 8, wherein the aperture is rectangular.
- 12. (Original) The semiconductor package assembly of Claim 8, wherein the windowframe capacitor comprises a housing.
- 13. (Original) The semiconductor package assembly of Claim 12, wherein the windowframe capacitor comprises a capacitive material disposed within the housing.

- 14. (Original) The semiconductor package assembly of Claim 13, wherein the capacitive material comprises a layer of an electrically conductive material and a layer of a dielectric material.
- 15. (Original) The semiconductor package assembly of Claim 14, wherein the housing is made of a plastic material.
- 16. (Original) The semiconductor package assembly of Claim 13, wherein the capacitive material and the housing comprise a co-fired ceramic.
- 17. (Original) The semiconductor package assembly of Claim 8, wherein the windowframe capacitor is mounted on the package substrate via a ball grid array.
- 18. (Canceled)